

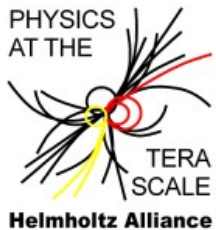
Measurements during the October test beam with the GEM-TPC and Timepix

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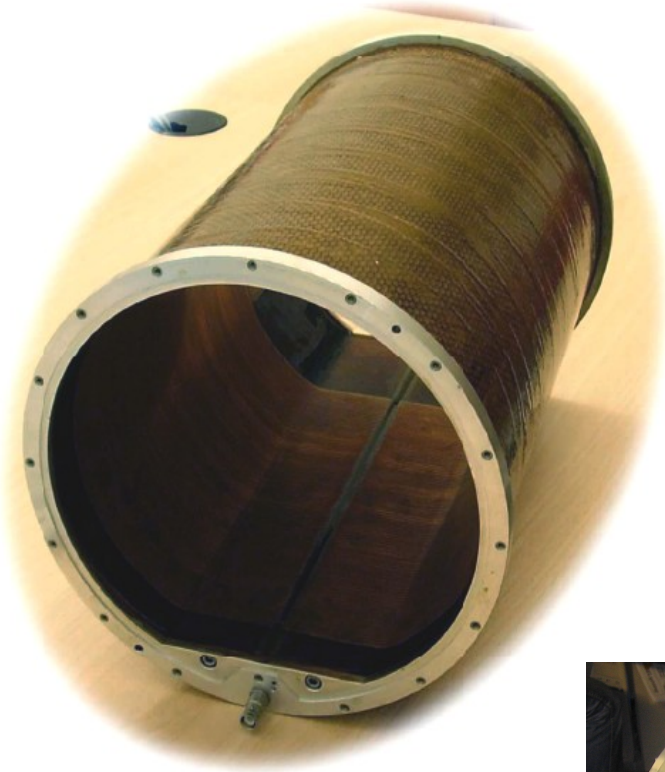


GEFÖRDERT VOM



RD-51 collaboration meeting, WG-7
CERN, 24. November 2009

TPC Prototype at Bonn



Drift cylinder:

- drift distance: 26 cm
- inner diameter: 23 cm
- material budget: 1 % X_0

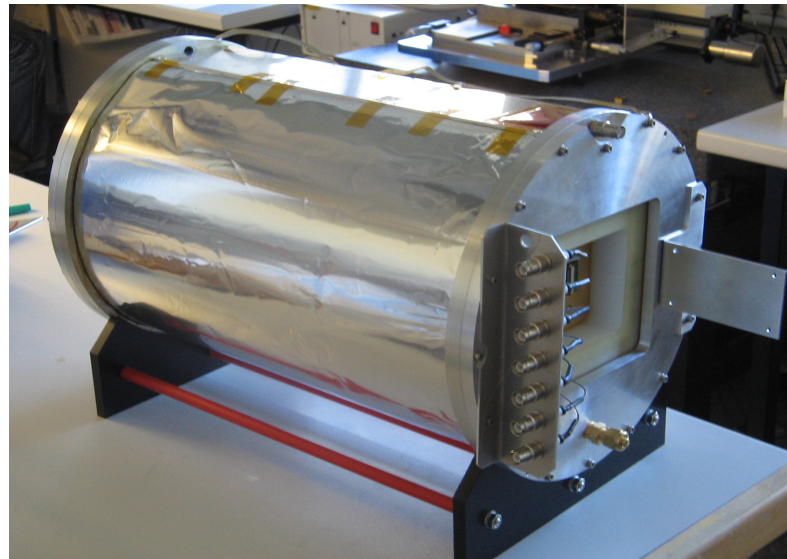
Gas amplification:

- 3 GEMs 1mm apart

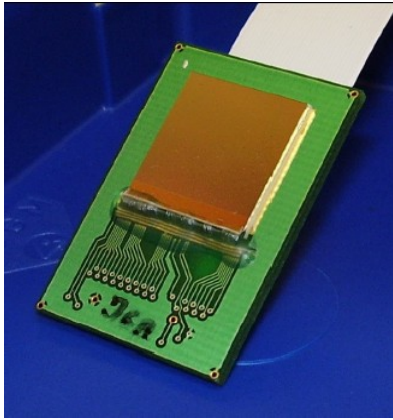
Currently:

He : CO₂ 70:30

E_{diff} : 500 V/cm



Detector: TPC



256 × 256 pixel

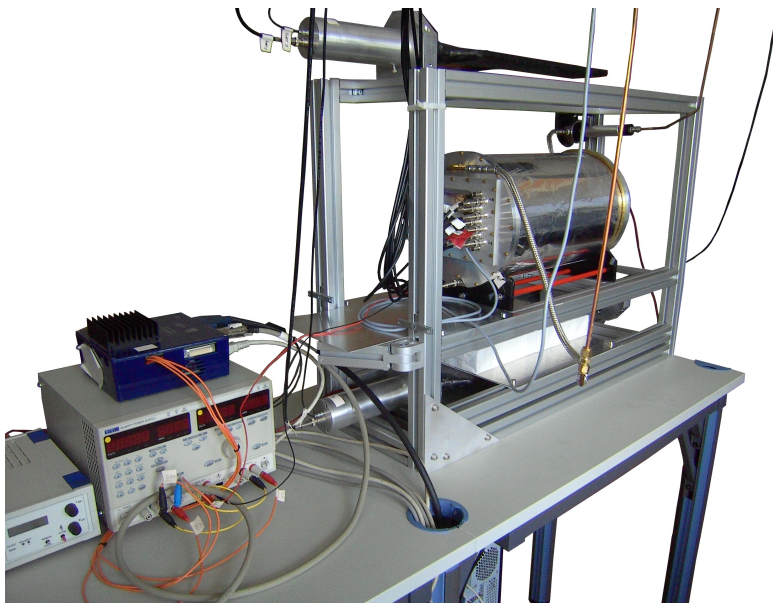
pixel size: $55 \times 55 \mu\text{m}^2$

chip dimensions: $1.4 \times 1.4 \text{ cm}^2$

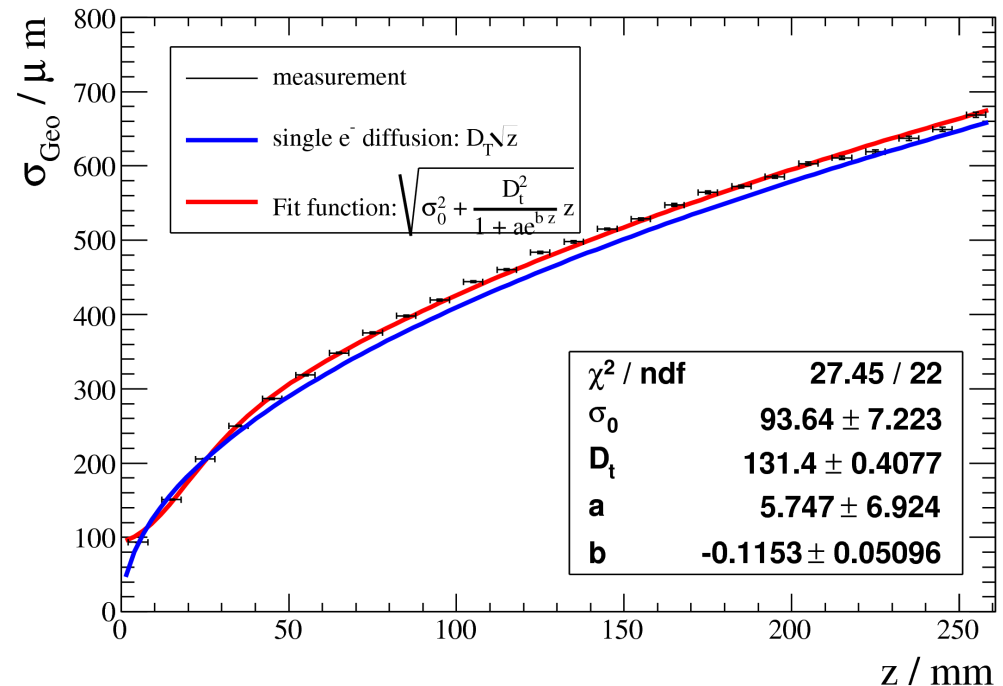
Operated in checker-board pattern of
TOT (charge) and **Time**

Cosmic ray test stand:

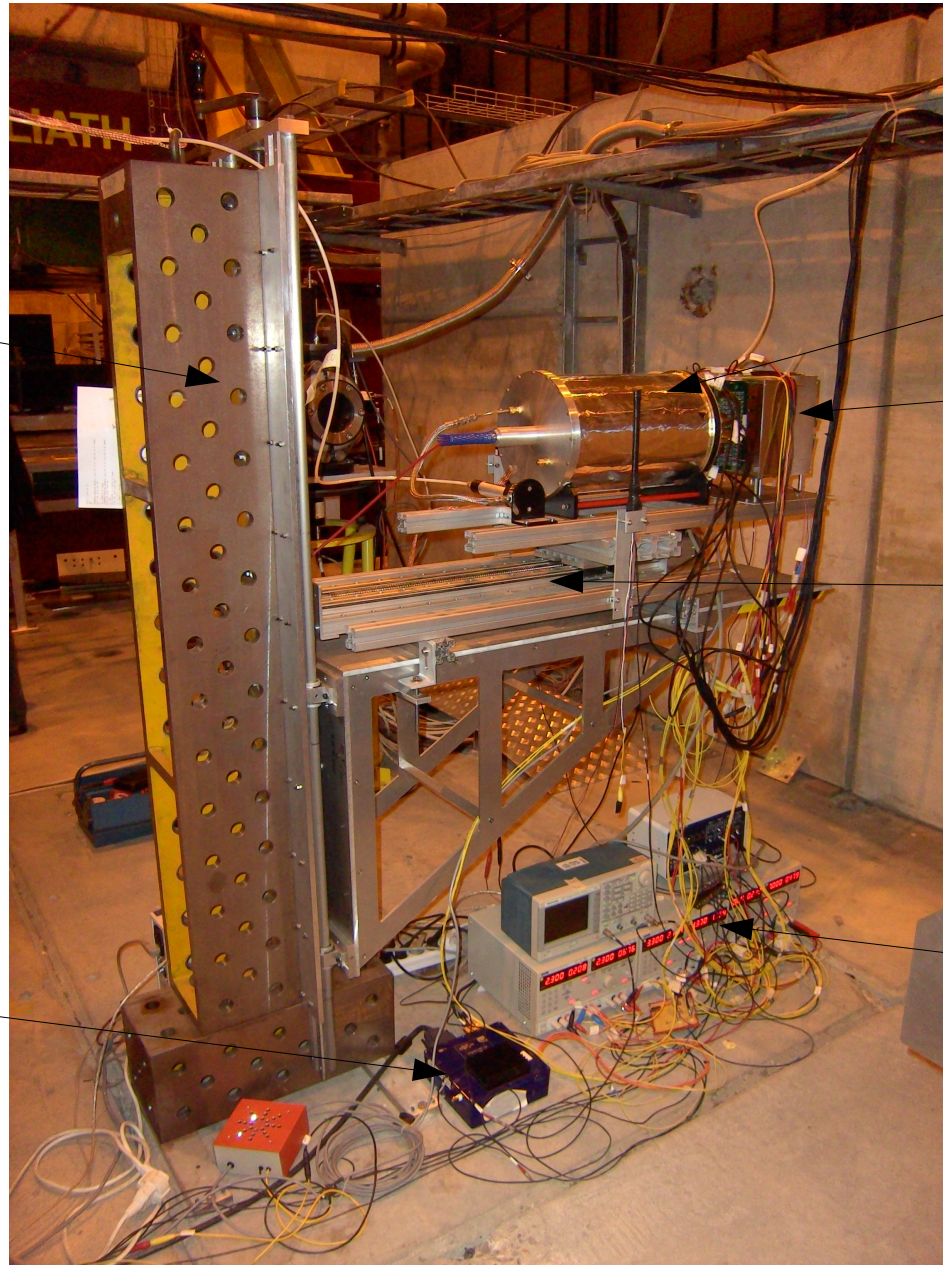
~ 1 month for 80,000 tracks



Distribution of Geometric Mean Resolution



Setup in the Test Beam Area



lifting stage

TPC

Altro frontend electronics

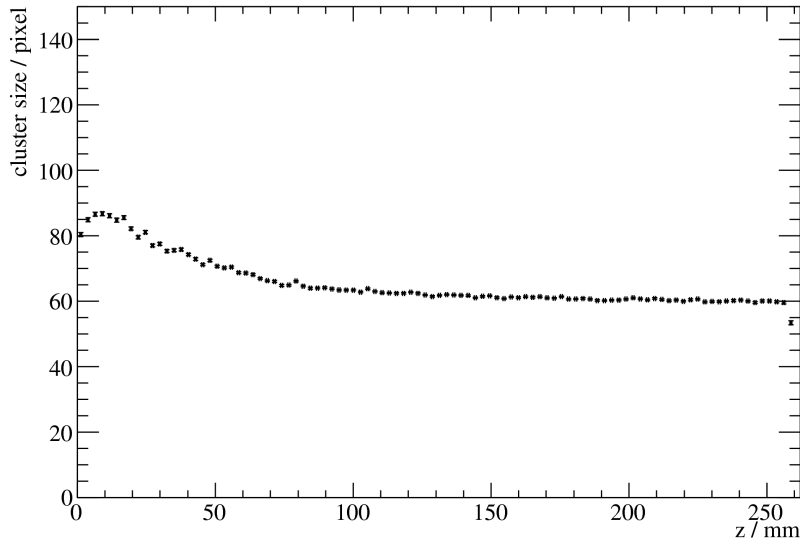
movable table

MUROS

readout electronics

LV power supplies

Goal 1 for Test Beam: Larger Pixel Sizes



Charge depositions are spread over ~60 pixels

=> pixel sizes are too small

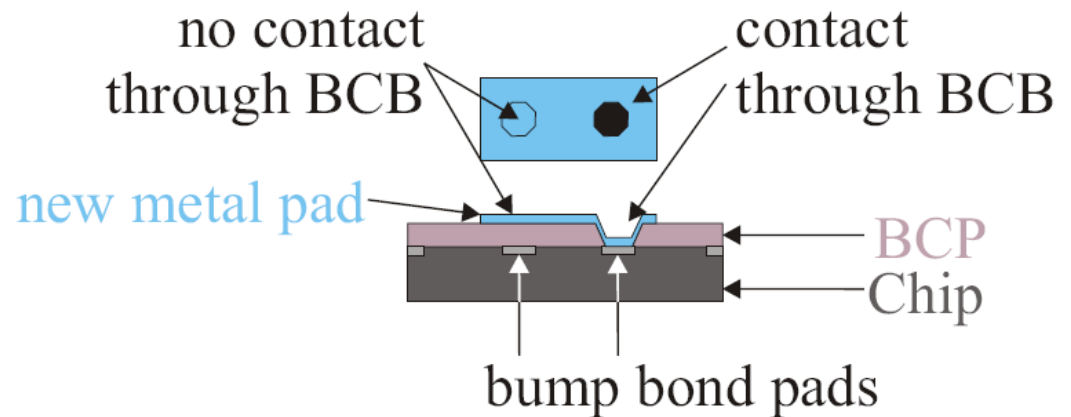
for the charge clouds generated by a triple GEM stack

=> high gains (60,000 – 100,000) are necessary for the signal to pass over threshold of pixels

TEST CHIPS WITH LARGER PIXELS

expensive to design new chips

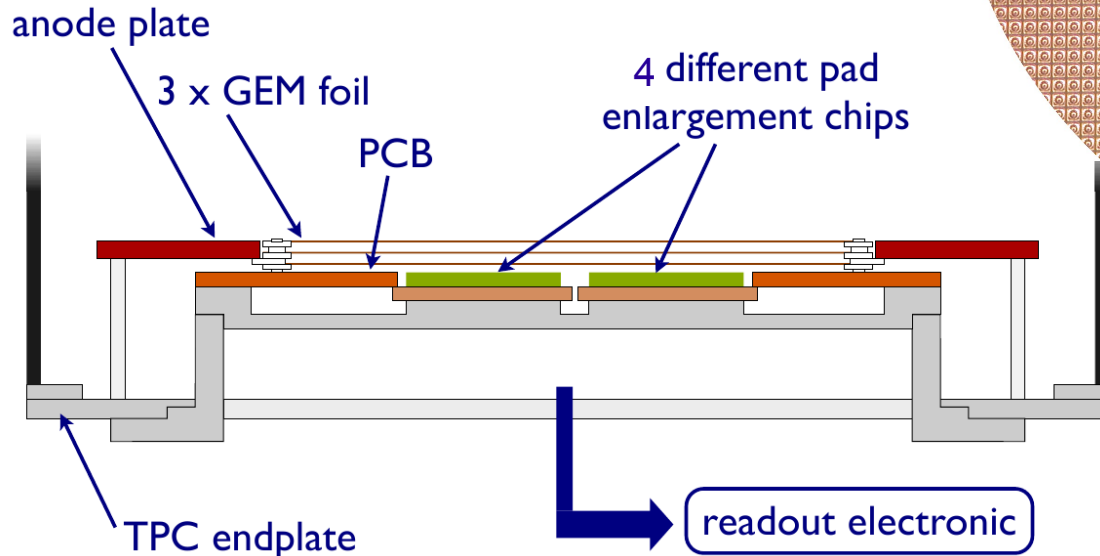
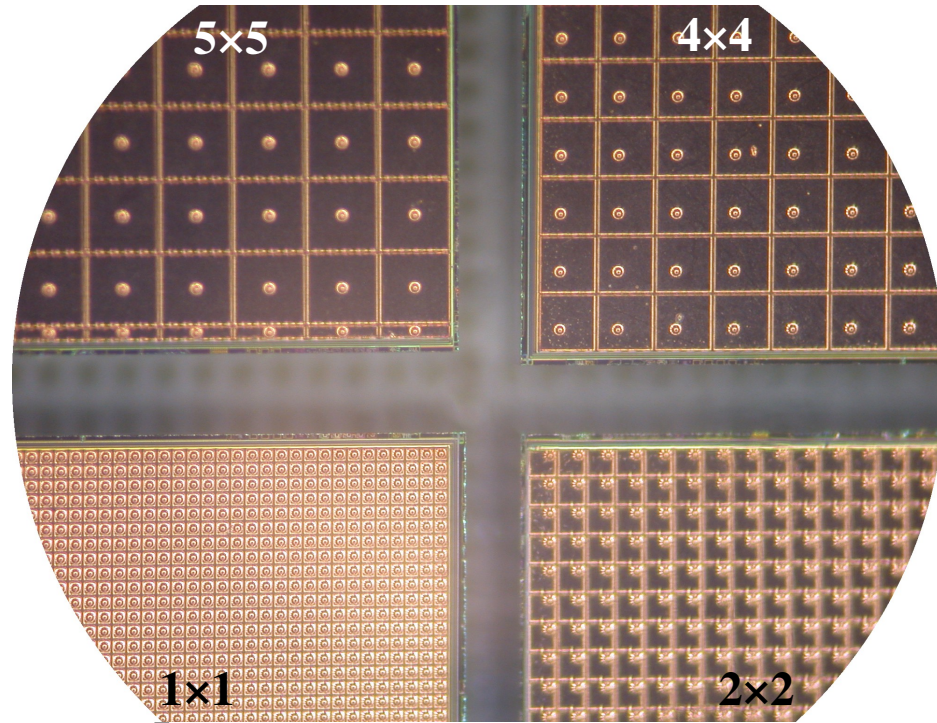
easier to combine pixels by adding new layers



Timepix with Larger Pixels



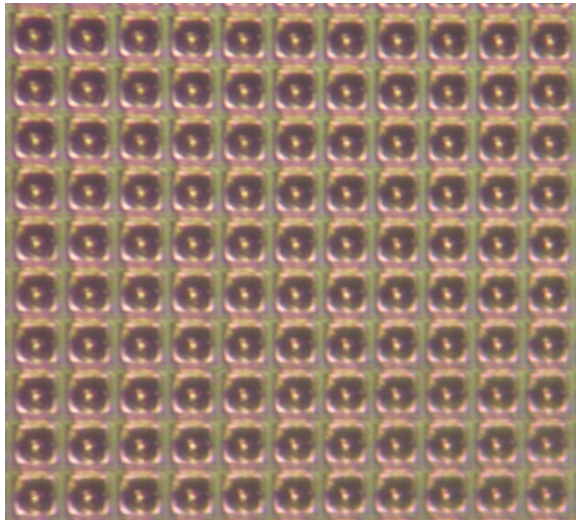
- 9 different geometries have been produced by IZM, Berlin.
- 4 have been tested during the test beam: 1×1 (for comparison), 2×2, 4×4, 5×5



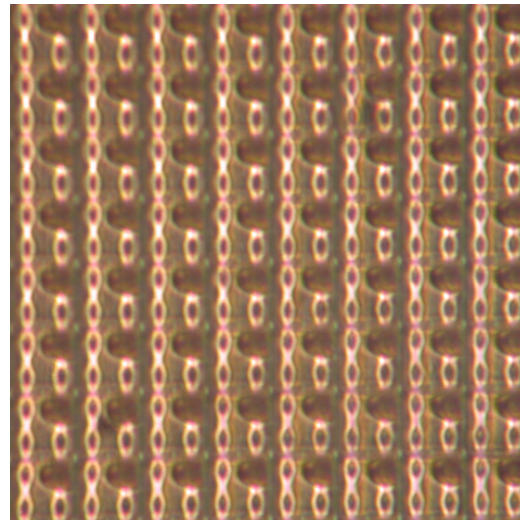
Closeup View of Chips



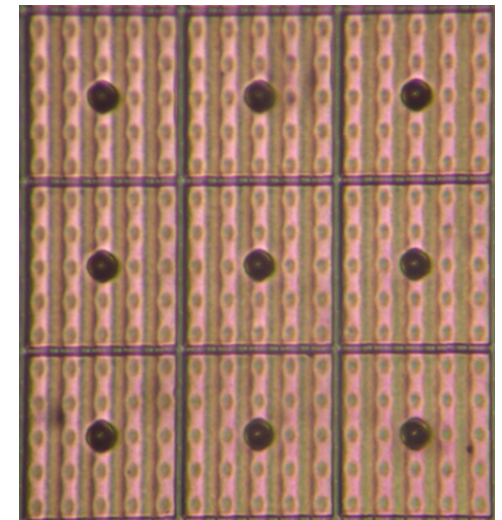
1×1-chip



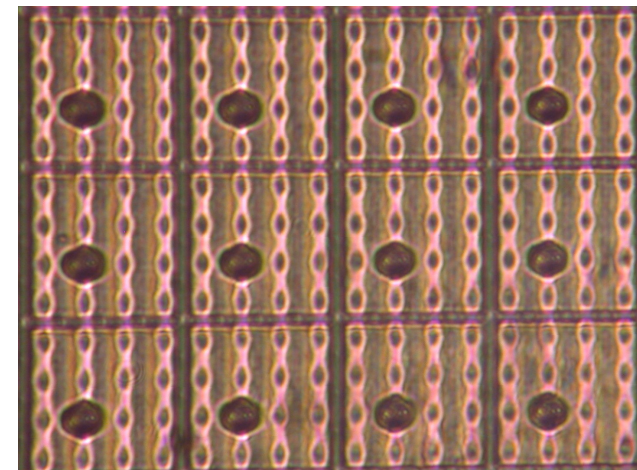
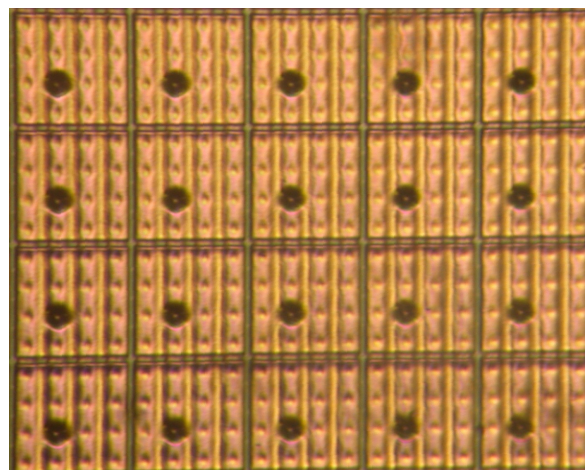
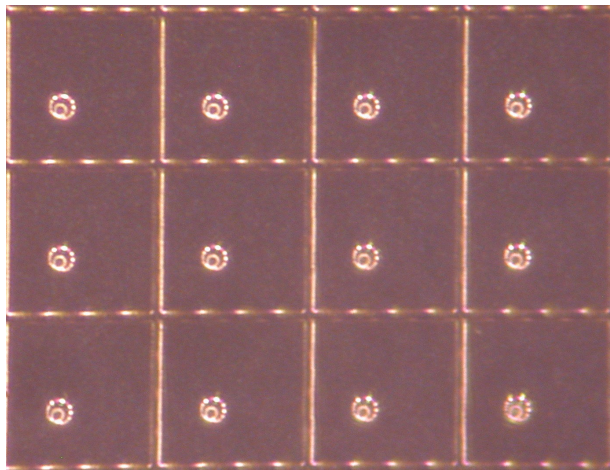
2×2-chip



5×5-chip



4×4-chip seen with different incidence of light

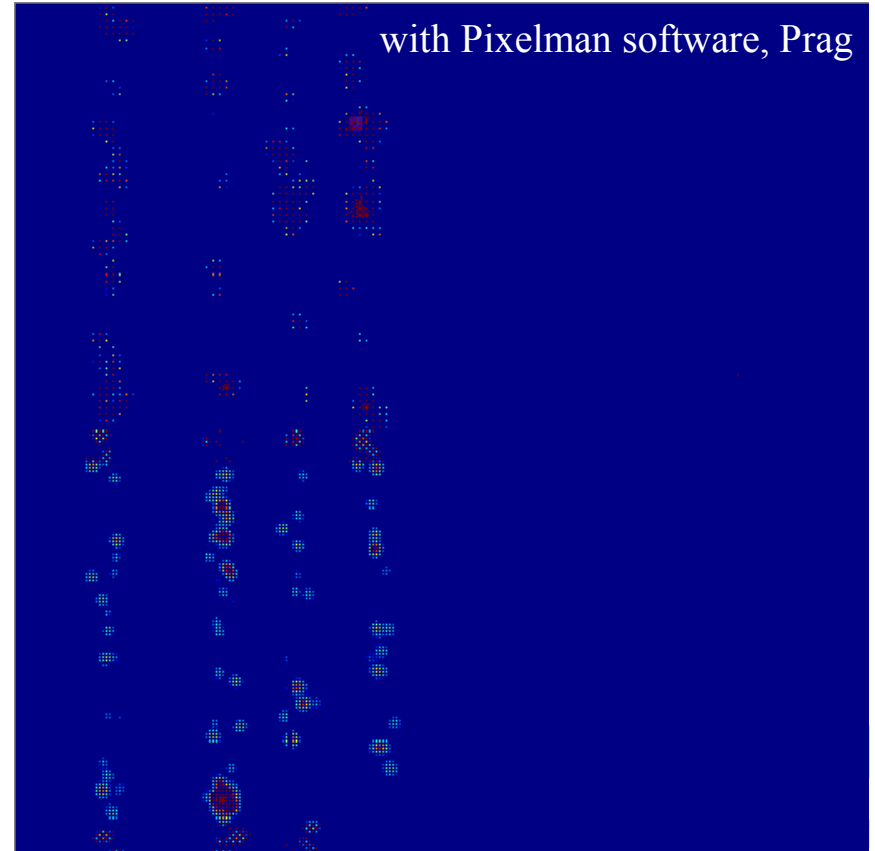
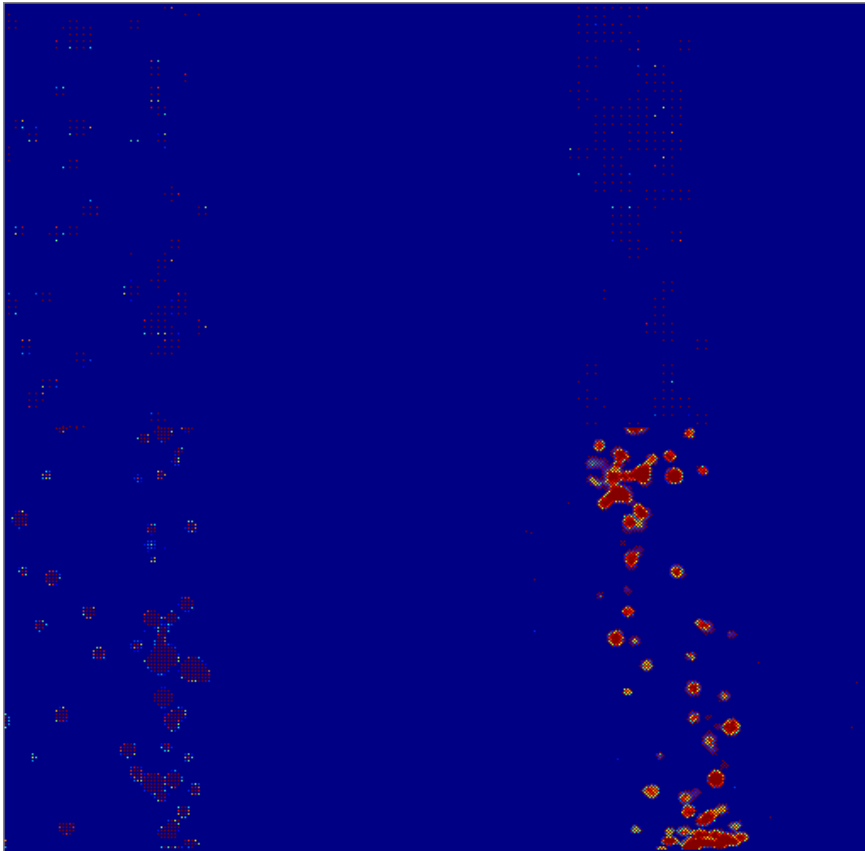


Some Pictures from the Online Display



- muons at 150 GeV
- drift distance: 25 cm
- 425 V across each GEM

- muons at 150 GeV
- drift distance: 5 cm
- 425 V across each GEM



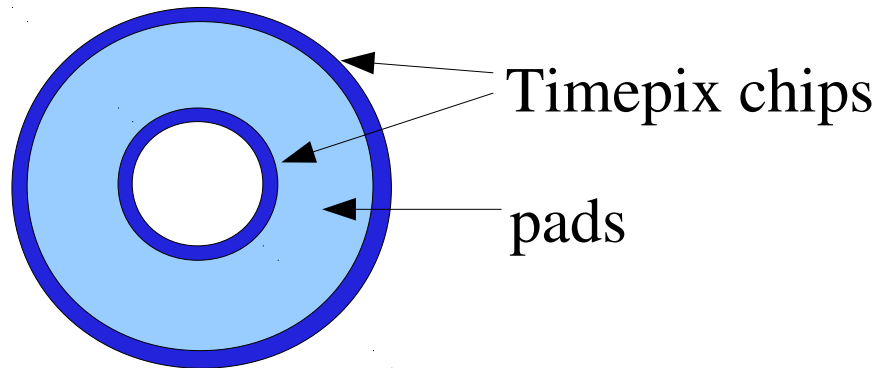
Goal 2 for the test beam:



Combination Pads and Pixels

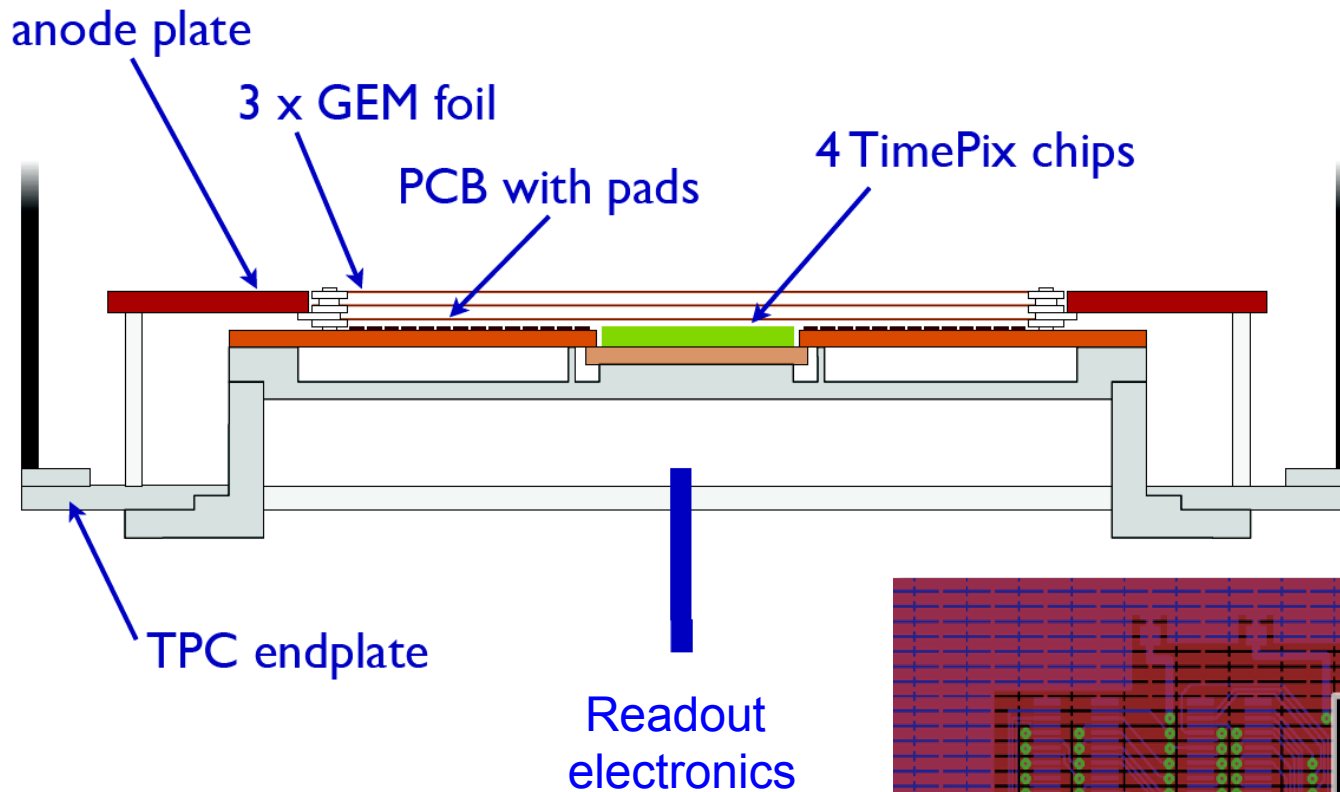
Large number of pixels may not be necessary everywhere on the TPC endcap.

Maybe only 2 rings are sufficient:

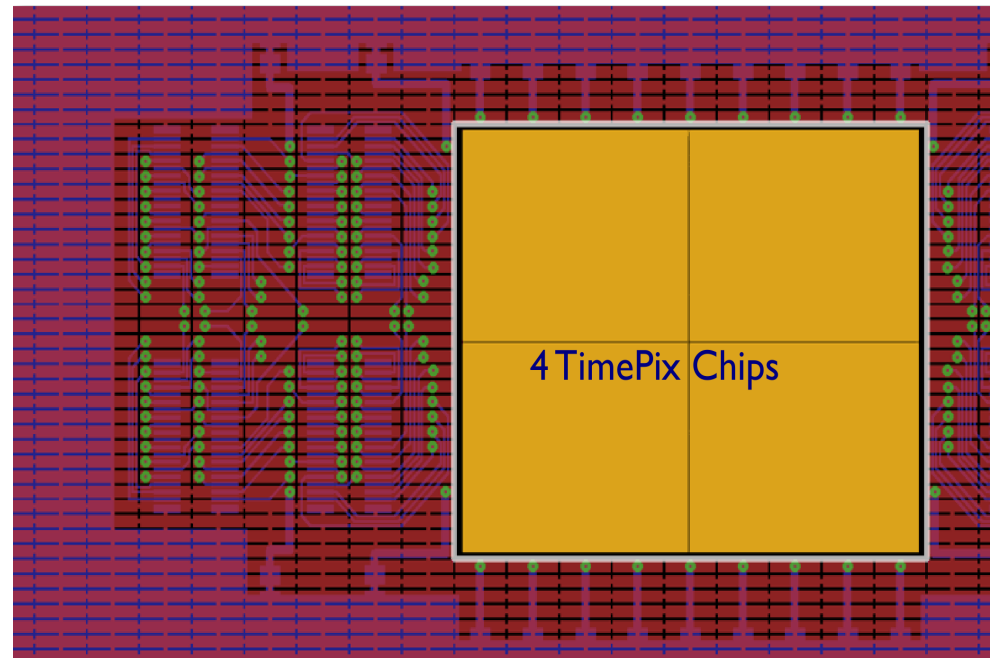


Combination of both pixels and pads on one endcap.

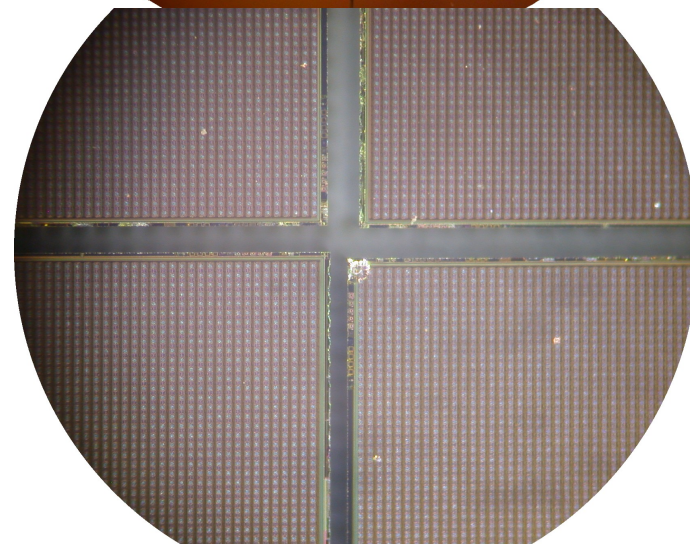
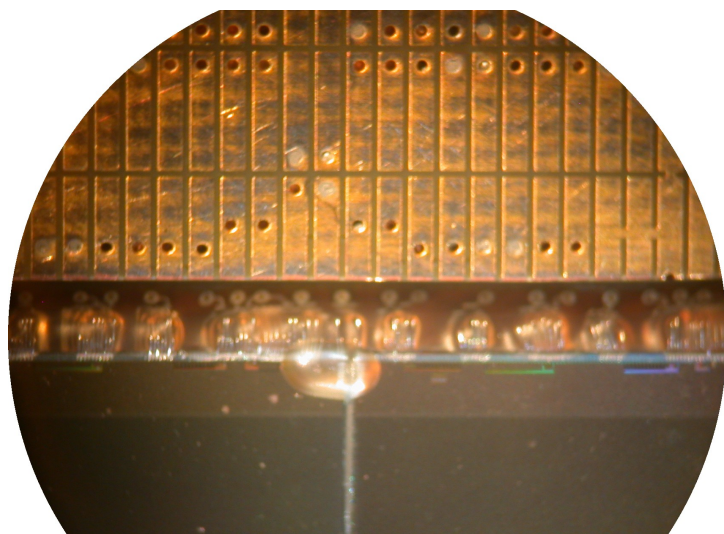
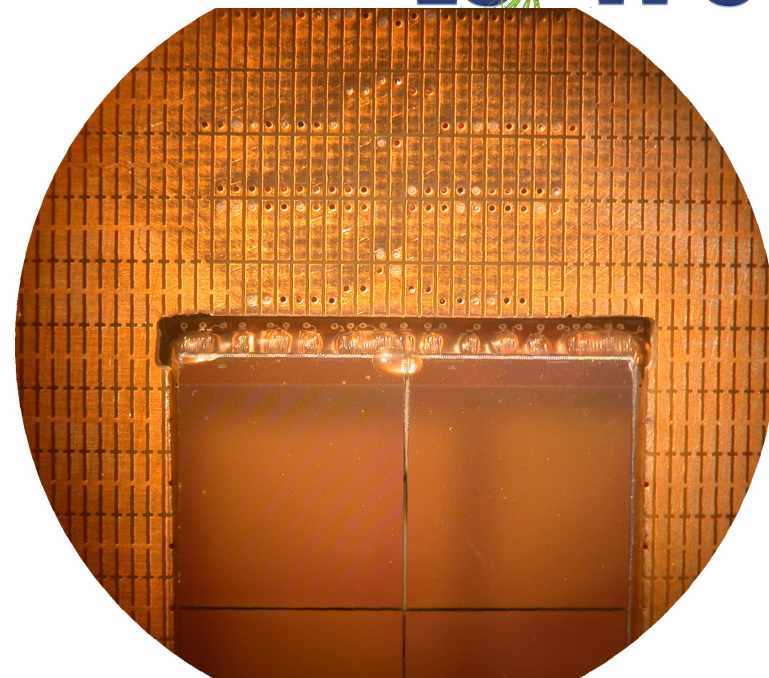
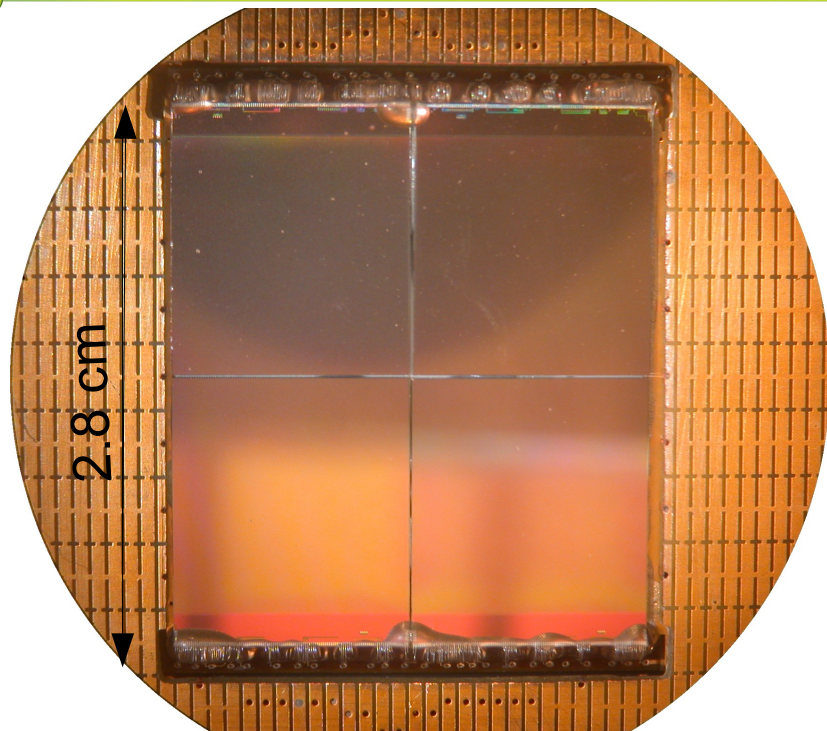
Test Combination of Pixels and Pads



- Pad sizes $4 \times 1 \text{ mm}^2$
connected to 256 channels
of ALTRO electronics
- 4 Timepix chips in the middle



Pictures from the Readout



Voltage Scan as Seen by Online Monitor



150 GeV muons after drifting 25 cm

370 V

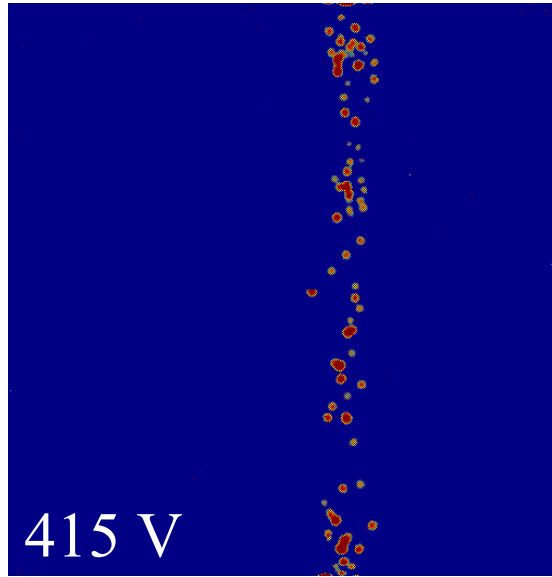
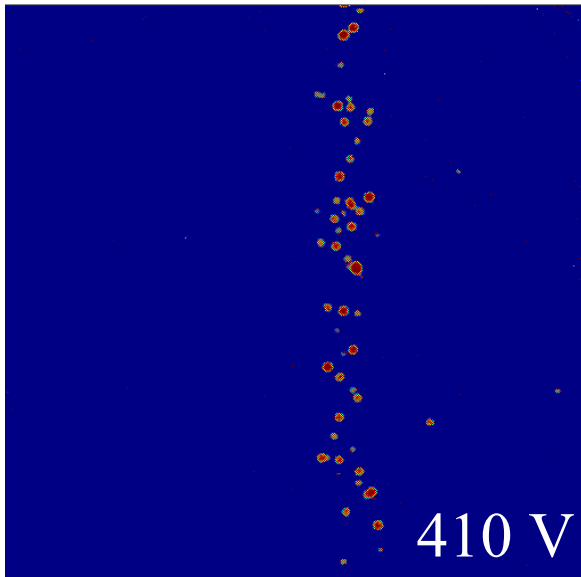
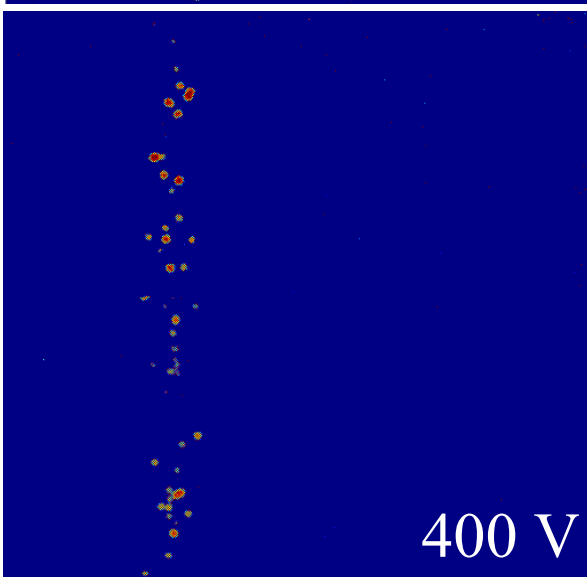
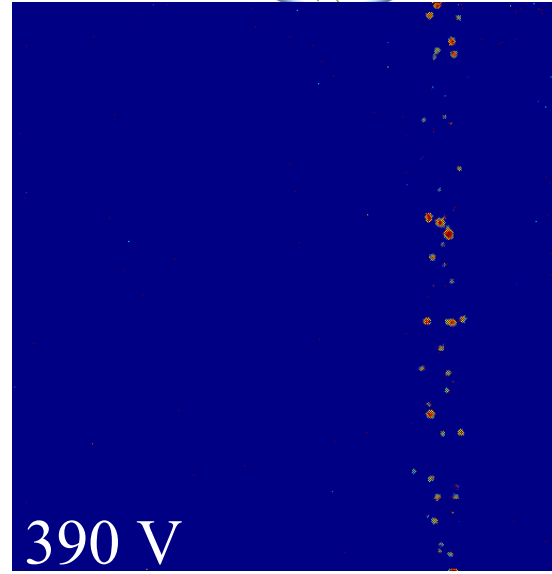
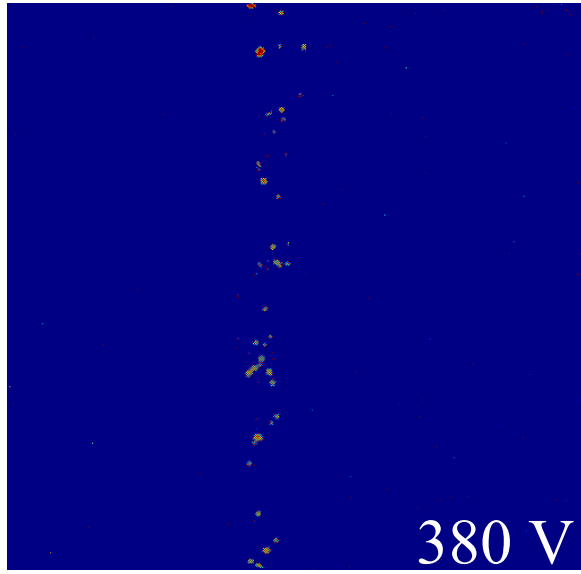
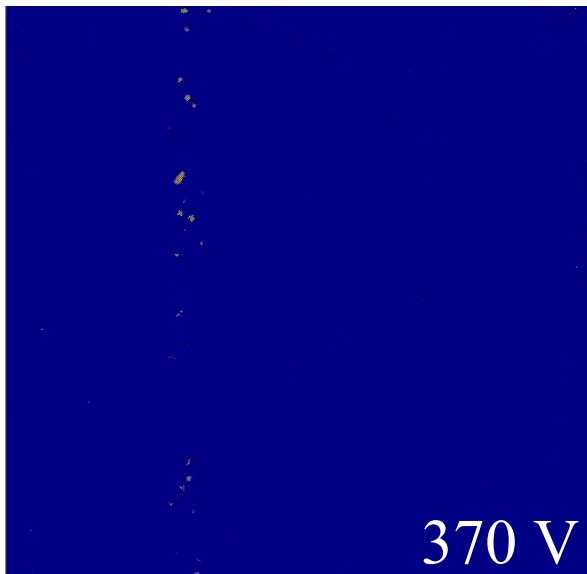
380 V

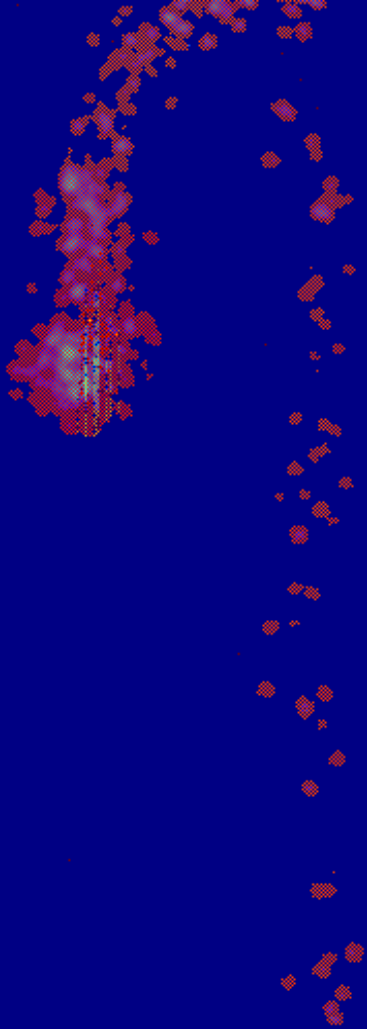
390 V

400 V

410 V

415 V





In both cases we took the following data:

- increasing the voltage at short (5 cm) and long (25 cm) drift distances
- changing the drift distance (5 - 25 cm in ~ 1 cm steps) at high voltages
- changing the track inclination in the readout plane

About 1,000 – 2,000 events per measurement

Analysis has started.